

## ABSTRACT OF THE DISCLOSURE

A semiconductor device in which semiconductor chip(s) is or are mounted onto substrate(s) incorporating patterned wiring and the entirety or entireties has or have been sealed with resin(s), wherein by forming electrically conductive pattern(s) for shielding at end face(s) at top(s) of substrate(s) and attaching such electrically conductive pattern(s) to region(s) of ground plane pattern(s) on circuit board(s) of apparatus(es) which is or are provided with such semiconductor device(s), it is possible to shield semiconductor device(s) even without use of shield case(s). In such case, by applying material(s) possessing good shielding characteristics, e.g., gold plating, over electrically conductive pattern(s), it is possible to increase sensitivity with respect to electromagnetic noise and improve shielding effect (anti-electromagnetic-noise effect).